

YES-CV200RFS PLASMA STRIP/DESCUM SYSTEM

Powerful Cleaning Removes Photoresist, Polyimide and BCB; With Gentle Descum Function

	SPECIFICATIONS
HARDWARE	
Clean Room Compatibility	Class 10
Wafer Temperature Range	Ambient to 250 °C
Capacity	Single wafer/pieces for 50mm - 200mm; Dual wafer/pieces for two 100mm
N2 Flow Rate	1.7 SCFM
Process Gas Flow Rate	20-50 SCCM average
Process Gas Inputs	4 standard
Mass Flow Controllers	Optional, up to 4 for gas mixing
Interior Chamber Dimensions	25.4 cm (W) x 28.575 cm (D) x 4.978 cm (H) — (10" x 11.25" x 1.96")
Hot Plate Process Area	49 in² maximum (200mm wafer)
Overall System Dimensions	60.96 cm (W) x 109.3 cm, door open (D) x 114.3 cm (H) — (24" x 43" x 45")
Chamber Material	6061-T6 aluminum
Compliance	SEMI S2, CE, S8
SOFTWARE	
Tool Control	PLC control of valves, temperature set points, plasma generation power, auto operation, touch screen interface
Number of Recipes	12 with load/save/loop/link capability
Range of Exposure Time	0-1200 seconds (20 minutes)
Resolution of Timer Setting	1 second
PERFORMANCE	
RF Plasma Power	40 kHz, 100 - 1000 W capacitive, downstream
Process Pressure Measurement	Convection type pressure sensor, 0.1 mTorr to 1000 Torr (pressure measurement sensitive to process gas composition)
Vent Gas Consumption	0 SCF idle, 1.0 SCF peak, .44 SCF average
Reactant Gas Consumption	0 SCF idle, 4.2 x 10 ⁻³ peak and average
Heat Emission	920 watts average
Power Consumption with Pump	420W idle, 2100W peak, 1210W average
Throughput	1 wafer per minute (up to 200mm diameter), typically 90 seconds per wafer
Strip Rate	Up to 7,000 Angstroms per minute
Electron Shift	< 10mV electron shift in a 200A gate oxide variable plasma intensity
Uniformity (in wafer)	<10%
Cooling	Process chamber cooled by forced air convection
ADDITIONAL	
Power Requirements	200-250V, 20 amps, 50/60 Hz, 1 phase
Power Supply	Automatic frequency tuning
System Weight	147.42 kg (325 lbs)

Contact Us: We offer process demonstrations. If you would like to submit samples, please call us. We can run your samples and provide a detailed process report.

Yield Engineering Systems, Inc.

Call: 1-925-373-8353 (worldwide) or 1-888-YES-3637 (US toll free)

www.yieldengineering.com